



RF360
Europe GmbH

Data sheet

SAW RF filter

Base stations
LTE band 34

Series/type: B5306
Ordering code: B39202B5306U410

Date: June 13, 2019

Version: 2.1

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A Qualcomm – TDK Joint Venture

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1 Application

- RF filter for LTE band 34
- Unbalanced to unbalanced operation
- Low amplitude ripple
- Usable passband 15 MHz
- Matching required for operation at 50 Ω

2 Features

- Package Code DCC6C
- Package size 3.0 \pm 0.1 mm \times 3.0 \pm 0.1 mm
- Package height 1.1 \pm 0.125 mm
- Approximate weight 0.04 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Lead free soldering compatible with J-STD20C
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 1 (MSL1)

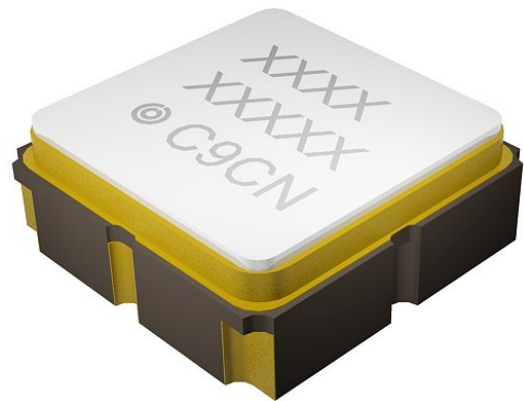
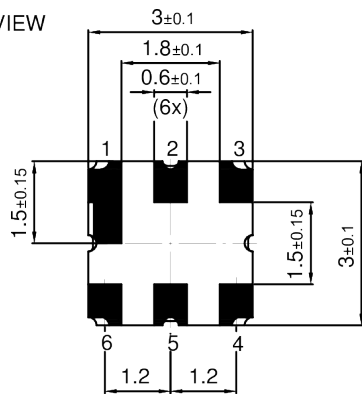


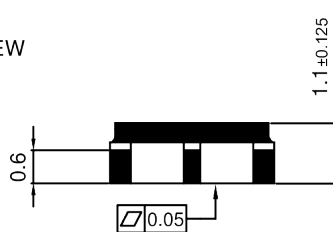
Figure 1: Picture of component with example of product marking.

3 Package

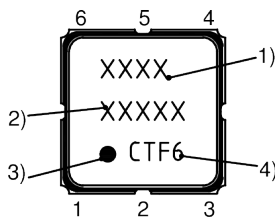
BOTTOM VIEW



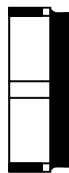
SIDE VIEW



TOP VIEW



SIDE VIEW



- 1) Device designation
- 2) Last five digits of the lot number
- 3) Marking for pad number 1
- 4) Example of production location and date code

Land pattern
 THRU VIEW

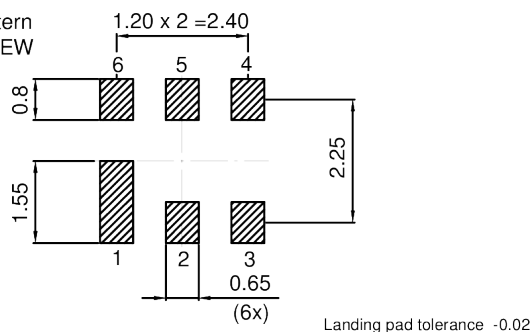


Figure 2: Drawing of package. See Sec. Package information (p. 17).

4 Pin configuration

- 2 Input
- 5 Output
- 1, 3, 4, 6 Ground

5 Matching circuit

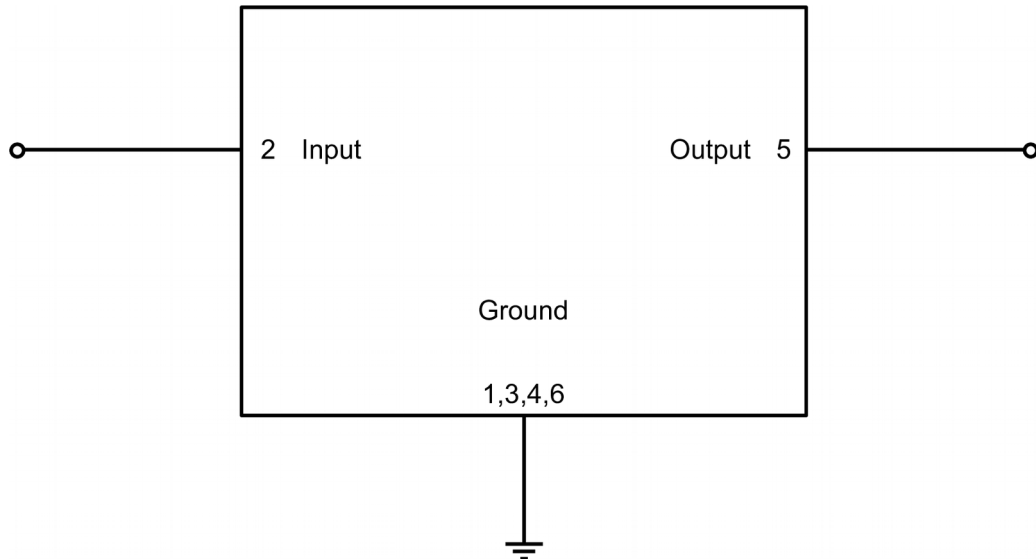


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

| | | |
|-------------------------------------|------------|---------------------|
| Temperature range for specification | T_{SPEC} | = -40 °C ... +95 °C |
| Input terminating impedance | Z_{IN} | = 50 Ω |
| Output terminating impedance | Z_{OUT} | = 50 Ω |

| Characteristics | | | | min. for T_{SPEC} | typ. @ +25 °C | max. for T_{SPEC} | |
|--------------------------------------|--------------|-----|----------------|------------------------|------------------|------------------------|-----|
| Center frequency | | | f_C | — | 2017.5 | — | MHz |
| Maximum insertion attenuation | | | α_{max} | | | | |
| | 2010... 2025 | MHz | | — | 2.2 | 3.5 | dB |
| Amplitude ripple (p-p) | | | $\Delta\alpha$ | | | | |
| | 2010... 2025 | MHz | | — | 0.3 | 1.2 | dB |
| Maximum VSWR | | | $VSWR_{max}$ | | | | |
| @ input port | 2010... 2025 | MHz | | — | 1.2 | 1.8:1 | |
| @ output port | 2010... 2025 | MHz | | — | 1.2 | 1.8:1 | |
| Minimum attenuation | | | α_{min} | | | | |
| | 1700... 1785 | MHz | | 40 | 53 | — | dB |
| | 1800... 1860 | MHz | | 45 | 60 | — | dB |
| | 1920... 1980 | MHz | | 30 | 32 | — | dB |
| | 1980... 1985 | MHz | | 24 | 32 | — | dB |
| | 2045... 2070 | MHz | | 6 | 25 | — | dB |
| | 2070... 2085 | MHz | | 40 | 55 | — | dB |
| | 2170... 4000 | MHz | | 30 | 35 | — | dB |

7 Maximum ratings

| | | |
|---------------------------------|---|---------------------------------------|
| Operable temperature | $T_{OP} = -40\text{ °C} \dots +125\text{ °C}$ | |
| Storage temperature | $T_{STG}^{1)} = -40\text{ °C} \dots +125\text{ °C}$ | |
| DC voltage | $ V_{DC} = 5.0\text{ V}$ | |
| ESD voltage | $V_{ESD}^{2)} = 100\text{ V}$ | Machine model. |
| Input power | P_{IN} | |
| @ input port: 2010 ... 2025 MHz | 15 dBm | Continuous wave for 100000 h @ 95 °C. |
| @ input port: 2010 ... 2025 MHz | 23 dBm | Continuous wave for 24 h @ 95 °C. |

¹⁾ Not valid for packaging material. Please refer to definition of Shelf life (p. 16).

²⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

8 Transmission coefficient

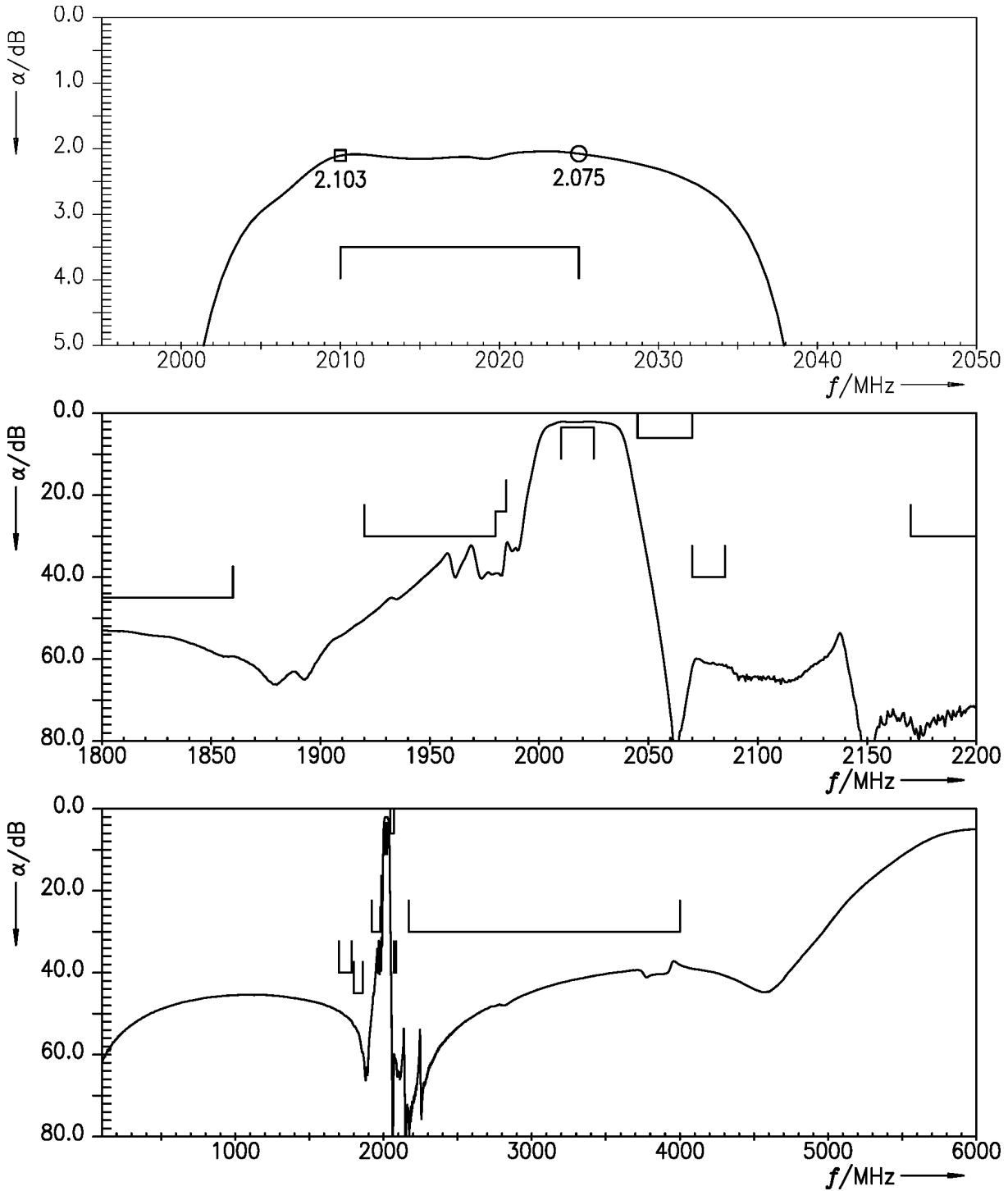


Figure 4: Attenuation.

9 Reflection coefficients

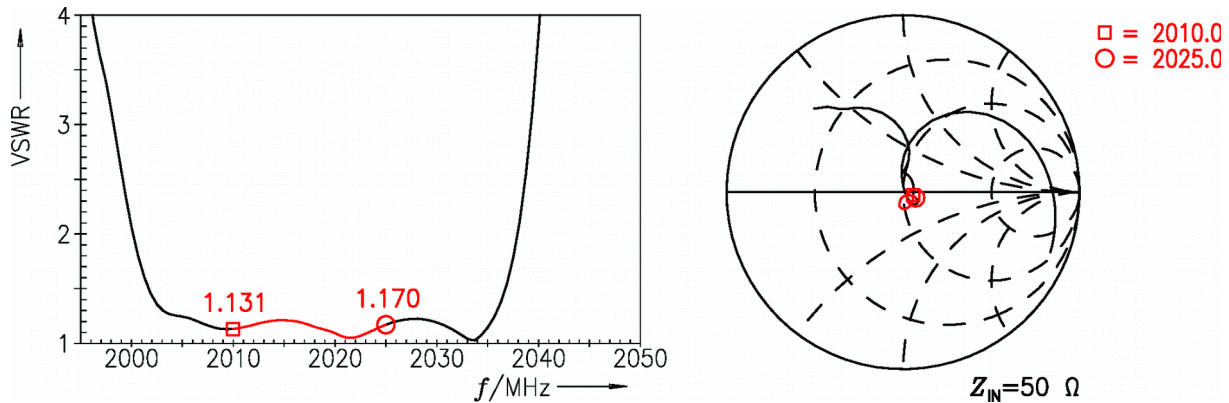


Figure 5: Reflection coefficient at input port.

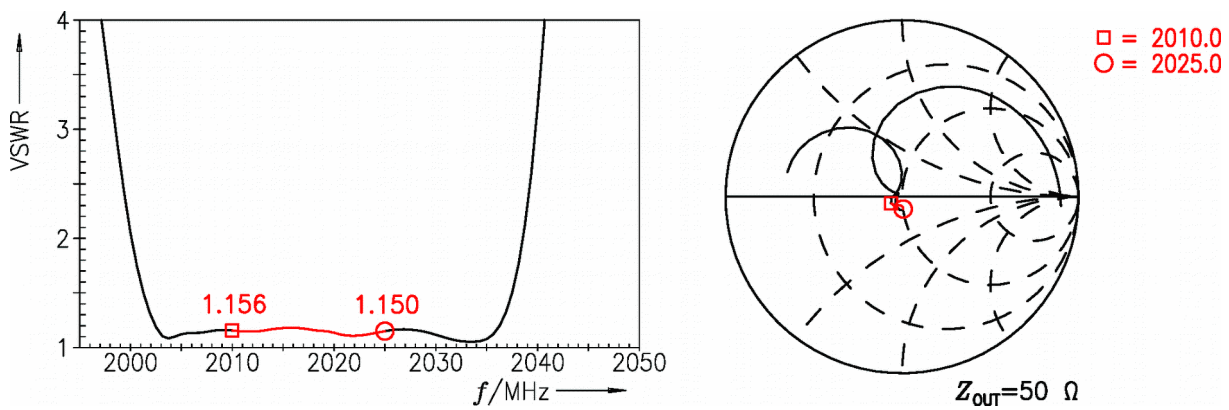


Figure 6: Reflection coefficient at output port.

10 Packing material

10.1 Tape

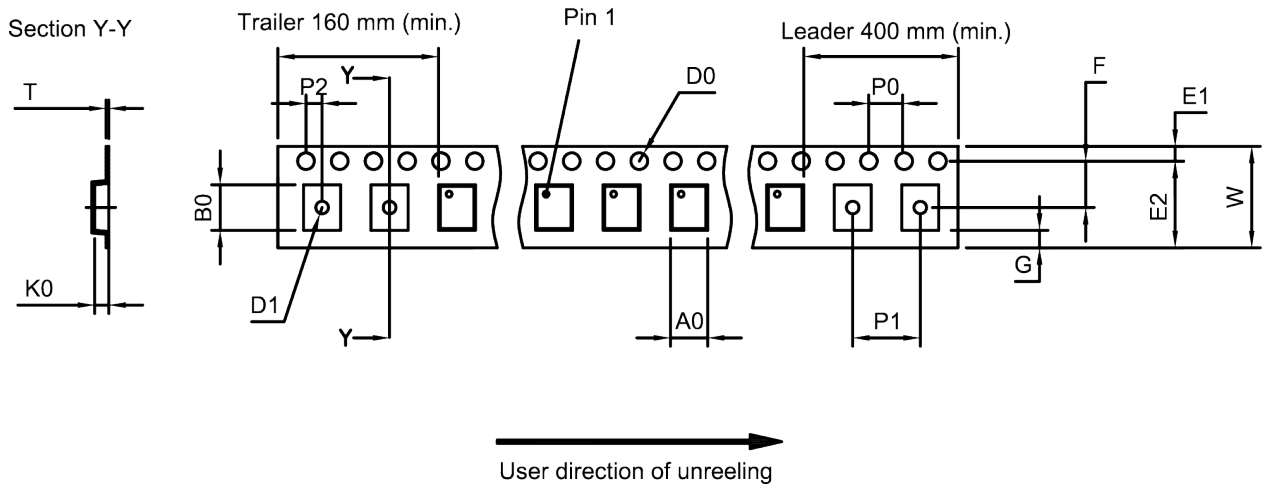


Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

| | | | | | |
|----------------|---------------|----------------|-----------------|----------------|------------------|
| A ₀ | 3.25±0.1 mm | E ₂ | 10.25 mm (min.) | P ₁ | 4.0±0.1 mm |
| B ₀ | 3.3±0.1 mm | F | 5.5±0.05 mm | P ₂ | 2.0±0.1 mm |
| D ₀ | 1.5+0.1/-0 mm | G | 0.75 mm (min.) | T | 0.3±0.05 mm |
| D ₁ | 1.5 mm (min.) | K ₀ | 1.5±0.1 mm | W | 12.0+0.3/-0.1 mm |
| E ₁ | 1.75±0.1 mm | P ₀ | 4.0±0.1 mm | | |

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

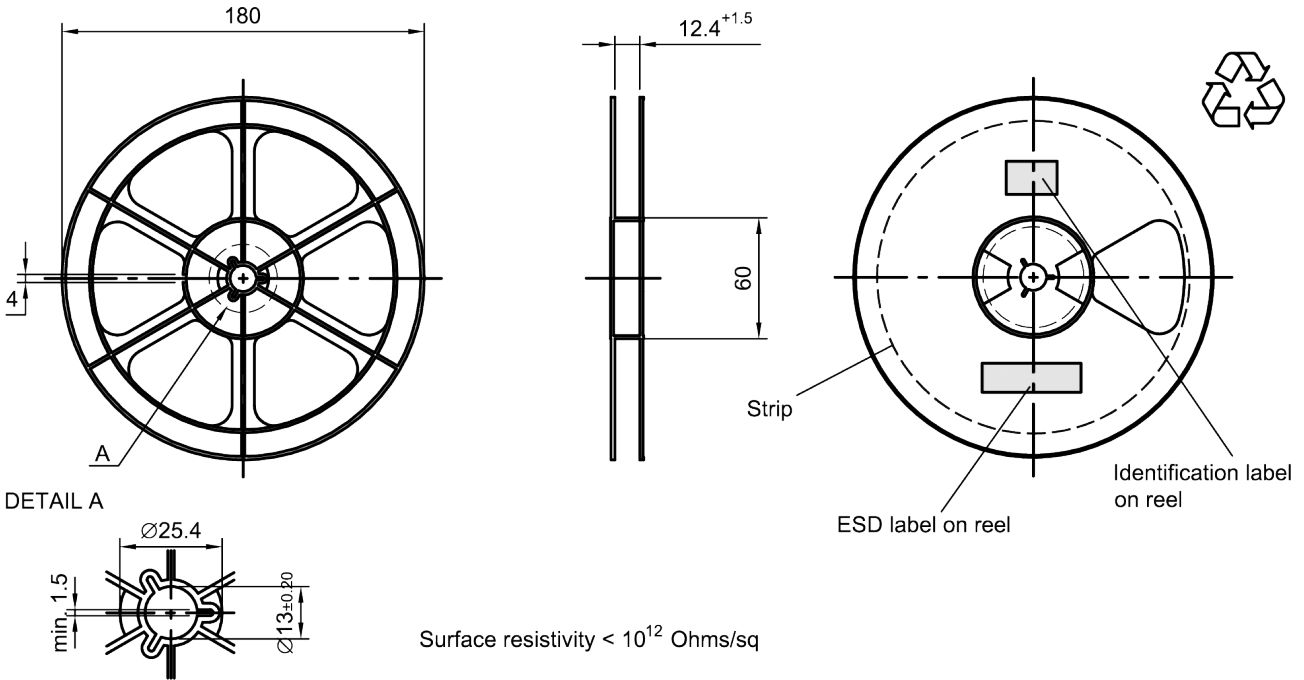
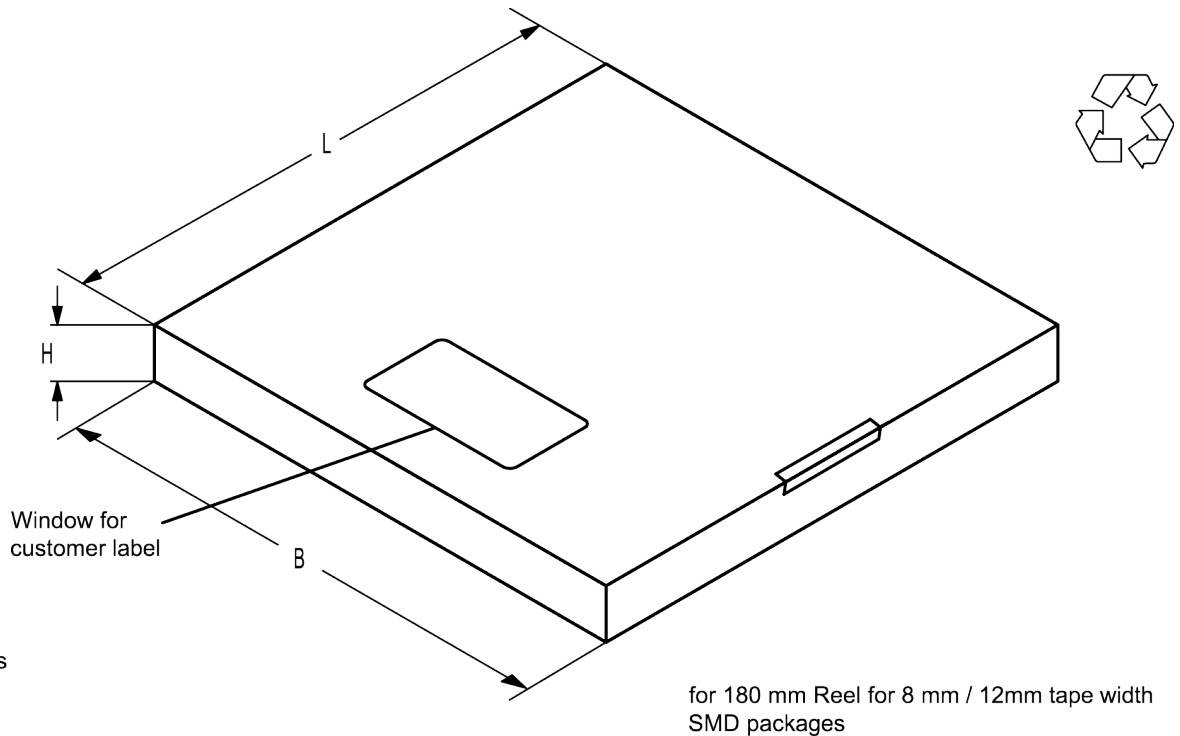


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.



Dimensions

- L = 182
- B = 185
- H = 26

Figure 9: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

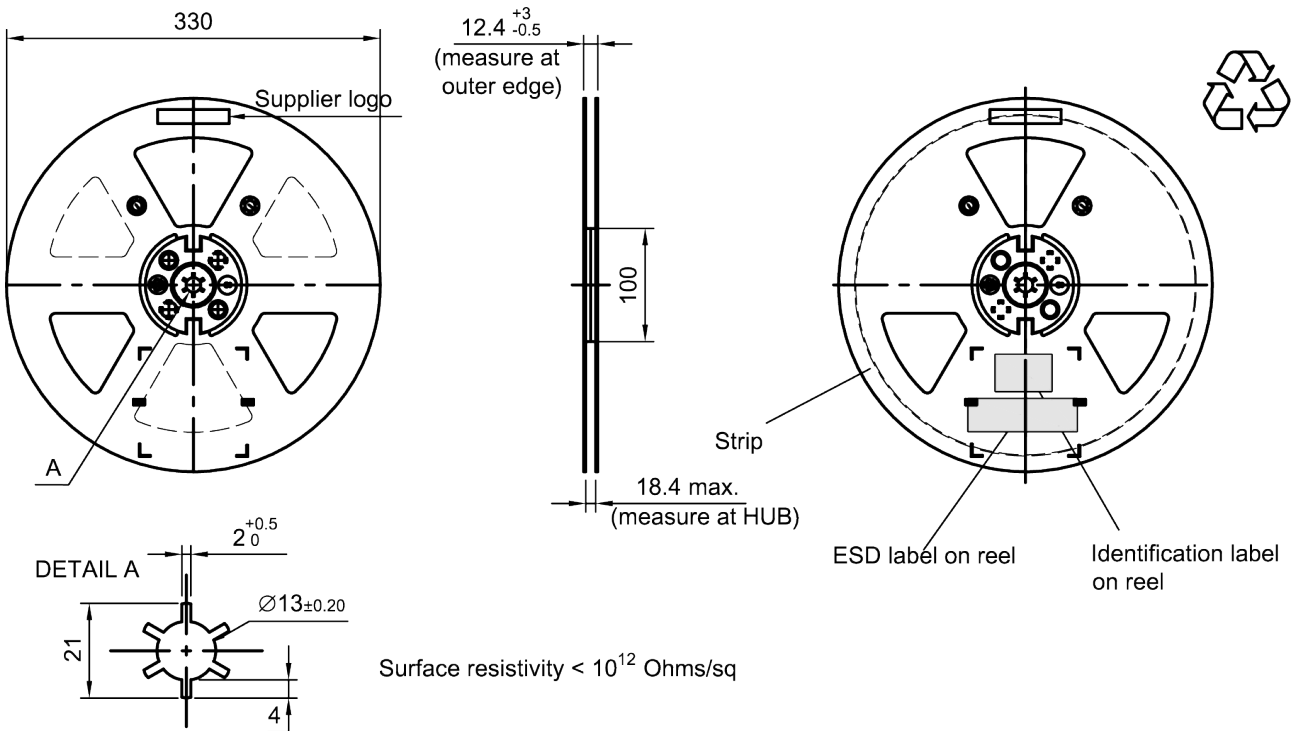
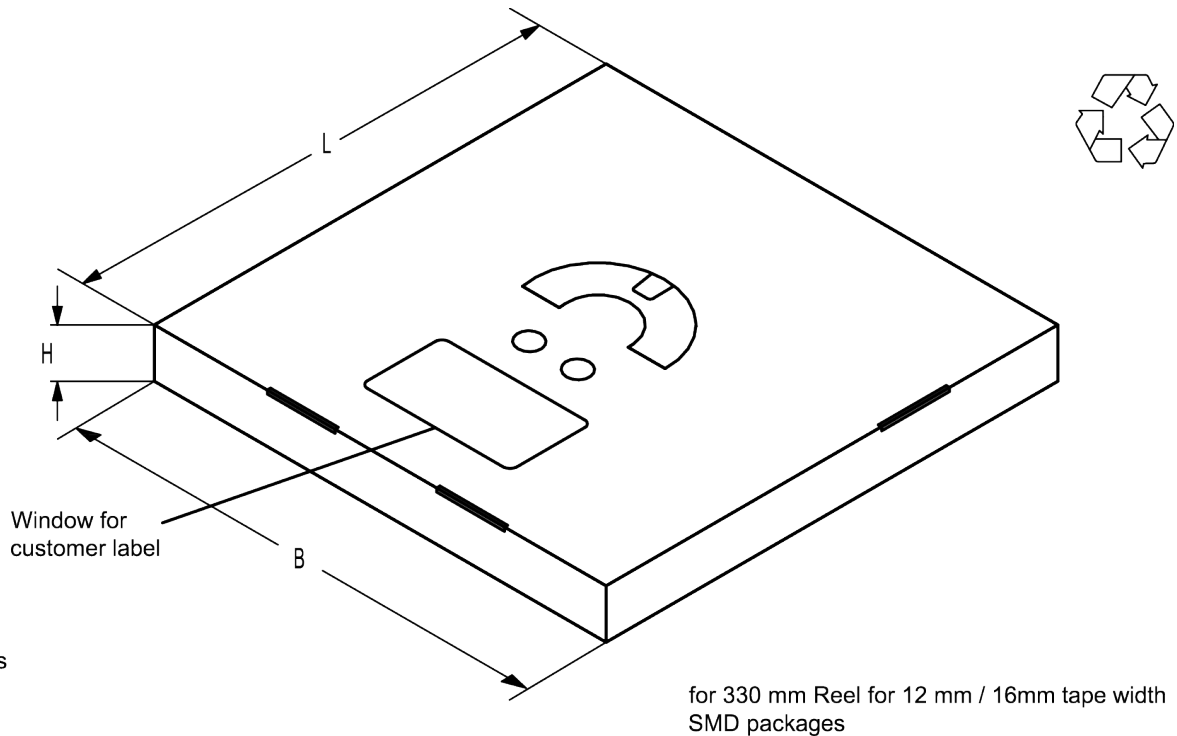


Figure 10: Drawing of reel (first-angle projection) with diameter of 330 mm.



Dimensions

- L = 340
- B = 340
- H = 25

for 330 mm Reel for 12 mm / 16mm tape width SMD packages

Figure 11: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with device designation, lot number, as well as production location and date code.

- Device designation: The 4-character device designation of the ordering code is used for the marking.

Example for 4-character device designation: B3xxxxB1234xxxx

- Lot number: The last 5 digits of the lot number are used for the marking.

Example: 12345

- Production location and date code: The production location is Wuxi (encoded in the first character 'C'). The production date code is encoded in the last three characters according to Table 2.

| 1 st digit (day) | | | | | | 2 nd digit (year) | | | | 3 rd digit (month) | | | |
|-----------------------------|------|-----|------|-----|------|------------------------------|------|-----------|------|-------------------------------|------|-------|------|
| Day | Code | Day | Code | Day | Code | Year | Code | Year | Code | Month | Code | Month | Code |
| 1 | 1 | 11 | A | 21 | M | 2010 | A | 2022 | P | Jan | 1 | Jul | 7 |
| 2 | 2 | 12 | B | 22 | N | 2011 | B | 2023 | R | Feb | 2 | Aug | 8 |
| 3 | 3 | 13 | C | 23 | P | 2012 | C | 2024 | S | Mar | 3 | Sep | 9 |
| 4 | 4 | 14 | D | 24 | R | 2013 | D | 2025 | T | Apr | 4 | Oct | 0 |
| 5 | 5 | 15 | E | 25 | S | 2014 | E | 2026 | U | May | 5 | Nov | N |
| 6 | 6 | 16 | F | 26 | T | 2015 | F | 2027 | V | Jun | 6 | Dec | D |
| 7 | 7 | 17 | H | 27 | U | 2016 | H | 2028 | W | | | | |
| 8 | 8 | 18 | J | 28 | V | 2017 | J | 2029 | X | | | | |
| 9 | 9 | 19 | K | 29 | W | 2018 | K | 2030 | Z | | | | |
| 10 | 0 | 20 | L | 30 | X | 2019 | L | 2031 | A | | | | |
| | | | | 31 | Z | 2020 | M | 2032 | B | | | | |
| | | | | | | 2021 | N | and so on | | | | | |

Table 2: Production date code.

Example of how to decode production location and date code:

Code: **C T F 6**

Location: C → Wuxi

Day: T → 26th

Year: F → 2015

Month: 6 → June

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

| | |
|-------------------------------|--|
| ramp rate | ≤ 3 K/s |
| preheat | 125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s |
| T > 220 °C | 30 s to 70 s |
| T > 230 °C | min. 10 s |
| T > 245 °C | max. 20 s |
| T ≥ 255 °C | – |
| peak temperature T_{peak} | 250 °C +0/-5 °C |
| wetting temperature T_{min} | 230 °C +5/-0 °C for 10 s ± 1 s |
| cooling rate | ≤ 3 K/s |
| soldering temperature T | measured at solder pads |

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

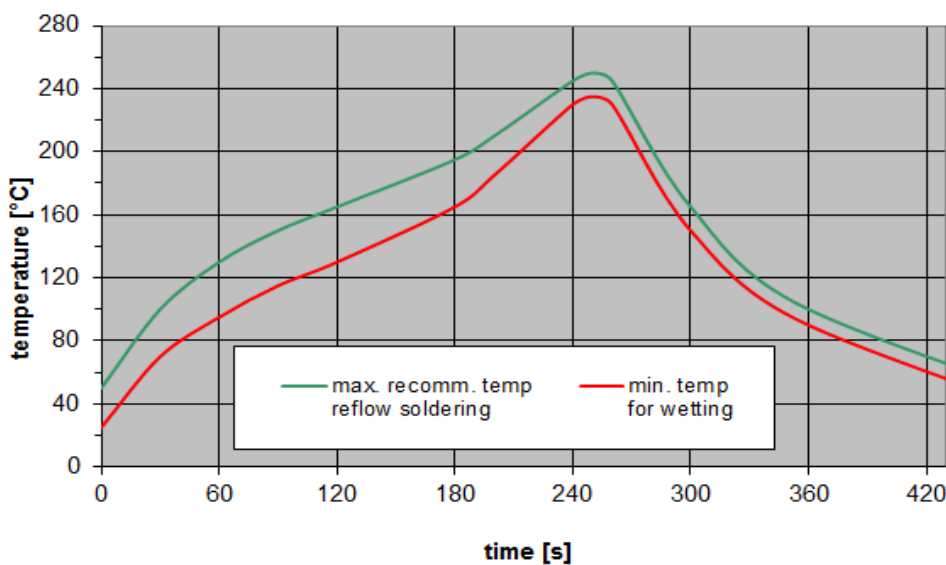


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Shelf life

The shelf life of components is determined by solderability of the package terminals. It is specified as 2 years from manufacturing date assuming the following conditions:

- storage in original packaging and non-aggressive atmosphere,
- storage temperature ranging from -25 °C to $+40\text{ °C}$, and
- storage humidity with $\leq 75\%$ r.h. mean annual humidity, $\leq 95\%$ r.h. for max. 30 days / year, and no dew condensation.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 Important notes

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